

Single and Dual Low Voltage, Rail-to-Rail Input and Output, Operational Amplifiers

LMV931, LMV932

The LMV931 Single and LMV932 Dual are CMOS low-voltage operational amplifiers which can operate on single-sided power supplies (1.8 V to 5.0 V) with rail-to-rail input and output swing. Both devices come in small state-of-the-art packages and require very low quiescent current making them ideal for battery-operated, portable applications such as notebook computers and hand-held instruments. Rail-to-Rail operation provides improved signal-to-noise performance plus the small packages allow for closer placement to signal sources thereby reducing noise pickup.

The single LMV931 is offered in space saving SC70-5 package. The dual LMV932 is in either a Micro8 or SOIC package. These small packages are very beneficial for crowded PCB's.

Features

- Performance Specified on Single-Sided Power Supply: 1.8 V, 2.7 V, and 5 V
- Small Packages:

LMV931 in a SC-70 LMV932 in a Micro8 or SOIC-8

- No Output Crossover Distortion
- Extended Industrial Temperature Range: -40°C to +125°C
- Low Quiescent Current 210 μA, Max Per Channel
- No Output Phase-Reversal from Overdriven Input
- These are Pb-Free Devices

Typical Applications

- Notebook Computers, Portable Battery-Operated Instruments, PDA's
- Active Filters, Low-Side Current Monitoring

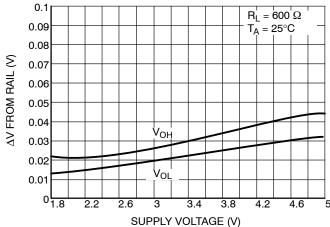


Figure 1. Output Voltage Swing vs. Supply Voltage

MARKING DIAGRAMS

LMV931 (Single)









TSOP-5 CASE 483

M = Date Code

A = Assembly Location

Y = Year

W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

LMV932 (Dual)



Micro8 CASE 846A





SOIC-8 CASE 751



A = Assembly Location

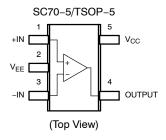
Y = Year
L = Wafer Lot
W = Work Week
■ Pb-Free Package

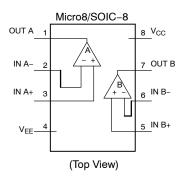
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 14 of this data sheet.

PIN CONNECTIONS





MAXIMUM RATINGS

Symbol	Rating		Value	Unit
Vs	Supply Voltage (Operating Range V _S = 1.8 V to 5.5 V)		5.5	V
V_{IDR}	Input Differential Voltage		± Supply Voltage	V
V _{ICR}	Input Common Mode Voltage Range		-0.5 to (V _{CC}) + 0.5	V
	Maximum Input Current		10	mA
t _{So}	Output Short Circuit (Note 1)		Continuous	
TJ	Maximum Junction Temperature (Operating Range -40°C to 85	°C)	150	°C
$\theta_{\sf JA}$	Thermal Resistance:	SC-70 ISOP-5 Micro8	280 333 238	°C/W
T _{stg}	Storage Temperature		-65 to 150	°C
	Mounting Temperature (Infrared or Convection ≤ 30 sec)		260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ESD data available upon request.

Continuous short—circuit operation to ground at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C. Output currents in excess of 45 mA over long term may adversely affect reliability. Shorting output to either V_{CC} or V_{EE} will adversely affect reliability.

1.8 V DC ELECTRICAL CHARACTERISTICS (Note 2) Unless otherwise noted, all min/max limits are guaranteed for $T_A = 25$ °C, $V_S = 1.8$ V, $V_{CM} = V_S/2$, $V_O = V_S/2$ and $R_L > 1$ M Ω . Typical specifications represent the most likely parametric norm.

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Input Offset Voltage	V _{IO}	LMV931 (Single) (-40°C to +125°C)		1	6	mV
		LMV932 (Dual) (-40°C to +125°C)		1	7.5	
Input Offset Voltage Average Drift	TCV _{IO}			5.5		μV/°C
Input Bias Current	Ι _Β	−40°C to +125°C		< 1		nA
Input Offset Current	I _{IO}	−40°C to +125°C		< 1		nA
Supply Current	I _{CC}	In Active Mode		75	185	μΑ
(per Channel)		-40°C to +125°C			205	
Common Mode	CMRR	$0 \text{ V} \le \text{V}_{\text{CM}} \le 0.6 \text{ V}, 1.4 \text{ V} \le \text{V}_{\text{CM}} \le 1.8 \text{ V}$	50	70		dB
Rejection Ratio		− 40°C to +125°C	50			
		$-0.2 \text{ V} \leq \text{V}_{\text{CM}} \leq 0 \text{ V}, 1.8 \text{ V} \leq \text{V}_{\text{CM}} \leq 2 \text{ V}$	50	70		
Power Supply	PSRR	$1.8 \text{ V} \le \text{V}^+ \le 5 \text{ V}, \text{V}_{\text{CM}} = 0.5 \text{ V}$	50	70		dB
Rejection Ratio		−40°C to +125°C	50			
Input Common-Mode Voltage Range	VcM	For CMRR ≥ 50 dB and T _A = 25°C	V _{EE} - 0.2	-0.2 to 2.1	V _{CC} + 0.2	V
		For CMRR ≥ 50 dB and T _A = - 40°C to +85°C	V_{EE}		V _{CC}	
		For CMRR \geq 50 dB and T _A = -40° C to $+125^{\circ}$ C	V _{EE} + 0.2		V _{CC} - 0.2	
Large Signal Voltage Gain LMV931 (Single)	A _V	R_L = 600 Ω to 0.9 V, V_O = 0.2 V to 1.6 V, V_{CM} = 0.5 V	77	101		dB
		-40°C to +125°C	73			
		R_L = 2 k Ω to 0.9V, V_O = 0.2 V to 1.6 V, V_{CM} = 0.5 V	80	105		
		-40°C to +125°C	75			
Large Signal Voltage	1	R_L = 600 Ω to 0.9 V, V_O = 0.2 V to 1.6 V, V_{CM} = 0.5 V	75	90		
Gain LMV932 (Dual)		-40°C to +125°C	72			
		R_L = 2 k Ω to 0.9 V, V_O = 0.2 V to 1.6 V, V_{CM} = 0.5 V	78	100		
		-40°C to +125°C	75			
Output Swing	V _{OH}	R_L = 600 Ω to 0.9V, V_{IN} = \pm 100 mV	1.65	1.72		V
		-40°C to +125°C	1.63			
	V _{OL}	R_L = 600 Ω to 0.9V, V_{IN} = \pm 100 mV		0.077	0.105	
		-40°C to +125°C			0.12	
	V _{OH}	R_L = 2 k Ω to 0.9V, V_{IN} = \pm 100 mV	1.75	1.77		
		−40°C to +125°C	1.74			
	V _{OL}	R _L = 2 kΩ to 0.9 V, V _{IN} = \pm 100 mV		0.24	0.035	1
		-40°C to +125°C			0.04	
Output Short Circuit	I _O	Sourcing, Vo = 0 V, V _{IN} = +100 mV	4.0	30		mA
Current		-40°C to +125°C	3.3			
		Sinking, Vo = 1.8V, V _{IN} = -100 mV	7.0	60		
		−40°C to +125°C	5.0			

^{2.} Guaranteed by design and/or characterization.

1.8 V AC ELECTRICAL CHARACTERISTICS Unless otherwise specified, all limits are guaranteed for $T_A = 25$ °C, $V_S = 1.8$ V, $V_{CM} = V_S/2$, $V_{O} = V_S/2$ and $R_L > 1$ M Ω . Typical specifications represent the most likely parametric norm. Min/Max specifications are guaranteed by testing, characterization, or statistical analysis.

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Slew Rate	SR	(Note 3)		0.35		V/μS
Gain Bandwidth Product	GBWP			1.4		MHz
Phase Margin	Θm			67		٥
Gain Margin	Gm			7		dB
Input-Referred Voltage Noise	e _n	f = 50 kHz, V _{CM} = 0.5 V		60		nV/√ Hz
Total Harmonic Distortion	THD	f = 1 kHz, A_V = +1, R_L = 600 Ω , V_O = 1 V_{PP}		0.023		%
Amplifier-to-Amplifier Isolation		(Note 4)		123		dB

^{3.} Connected as voltage follower with input step from V_{EE} to V_{CC} . Number specified is the slower of the positive and negative slew rates. 4. Input referred, $R_L = 100 \text{ k}\Omega$ connected to $V_S/2$. Each amp excited in turn with 1 kHz to produce $V_O = 3 V_{PP}$. (For Supply Voltages < 3 V, $V_O = V_{CC}$).

2.7 V DC ELECTRICAL CHARACTERISTICS (Note 5) Unless otherwise noted, all min/max limits are guaranteed for T_A = 25°C, V_S = 2.7 V, V_{CM} = $V_S/2$, V_O = $V_S/2$ and R_L > 1 M Ω . Typical specifications represent the most likely parametric norm.

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Input Offset Voltage	V _{IO}	LMV931 (Single) (-40°C to +125°C)		1	6	mV
		LMV932 (Dual) (-40°C to +125°C)		1	7.5	
Input Offset Voltage Average Drift	TCV _{IO}			5.5		μV/°C
Input Bias Current	Ι _Β	-40°C to +125°C		< 1		nA
Input Offset Current	I _{IO}	−40°C to +125°C		< 1		nA
Supply Current (per	I _{CC}	In Active Mode		80	190	μΑ
Channel)		−40°C to +125°C			210	
Common Mode	CMRR	$0~V \leq V_{CM} \leq 1.5~V, 2.3~V \leq V_{CM} \leq 2.7~V$	50	70		dB
Rejection Ratio		−40°C to +125°C	50			
		$-0.2~V \leq V_{CM} \leq 0~V, 2.7~V \leq V_{CM} \leq 2.9~V$	50	70		
Power Supply	PSRR	$1.8~V \leq V^+ \leq 5~V, V_{CM} = 0.5~V$	50	70		dB
Rejection Ratio		-40°C to +125°C	50			
Input Common-Mode Voltage Range	Vсм	For CMRR \geq 50 dB and T _A = 25°C	V _{EE} - 0.2	-0.2 to 3.0	V _{CC} + 0.2	٧
		For CMRR \geq 50 dB and T _A = -40°C to +85°C	V _{EE}		V _{CC}	
		For CMRR \geq 50 dB and T _A = -40° C to $+125^{\circ}$ C	V _{EE} + 0.2		V _{CC} - 0.2	
Large Signal Voltage Gain LMV931 (Single)	A _V	R_L = 600 Ω to 1.35 V, V_O = 0.2 V to 2.5 V	87	104		dB
		−40°C to +125°C	86			
		R_L = 2 $k\Omega$ to 1.35 V, V_O = 0.2 V to 2.5 V	92	110		
		−40°C to +125°C	91			
Large Signal Voltage	A_V	R_L = 600 Ω to 1.35 V, V_O = 0.2 V to 2.5 V	78	90		
Gain LMV932 (Dual)		−40°C to +125°C	75			
		R_L = 2 k Ω to 1.35 V, V_O = 0.2 V to 2.5 V	81	100		
		−40°C to +125°C	78			
Output Swing	V _{OH}	R_L = 600 Ω to 1.35 V, V_{IN} = \pm 100 mV	2.55	2.62		V
		−40°C to +125°C	2.53			
	V _{OL}	R_L = 600 Ω to 1.35 V, V_{IN} = \pm 100 mV		0.083	0.11	
	_	-40°C to +125°C			0.13	
	V _{OH}	R_L = 2 k Ω to 1.35 V, V_{IN} = \pm 100 mV	2.65	2.675		
	_	-40°C to +125°C	2.64			
	V _{OL}	R_L = 2 k Ω to 1.35 V, V_{IN} = \pm 100 mV		0.025	0.04	
		-40°C to +125°C			0.045	
Output Short Circuit	Io	Sourcing, Vo = 0 V, V _{IN} = ±100 mV	20	65		mA
Current		-40°C to +125°C	15			
		Sinking, Vo = 0 V, V _{IN} = -100 mV	18	75		
		-40°C to +125°C	12	<u> </u>		

^{5.} Guaranteed by design and/or characterization.

2.7 V AC ELECTRICAL CHARACTERISTICS Unless otherwise specified, all limits are guaranteed for $T_A = 25$ °C, $V_S = 2.7$ V, $V_{CM} = V_S/2$, $V_{CM} = V_S/2$ and $R_L > 1$ M Ω . Typical specifications represent the most likely parametric norm. Min/Max specifications are guaranteed by testing, characterization, or statistical analysis.

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Slew Rate	SR	(Note 6)		0.4		V/uS
Gain Bandwidth Product	GBWP			1.4		MHz
Phase Margin	Θm			70		٥
Gain Margin	Gm			7.5		dB
Input-Referred Voltage Noise	e _n	f = 50 kHz, V _{CM} = 1.0 V		57		nV/√Hz
Total Harmonic Distortion	THD	f = 1 kHz, A_V = +1, R_L = 600 Ω , V_O = 1 V_{PP}		0.022		%
Amplifier-to-Amplifier Isolation		(Note 7)		123		dB

^{6.} Connected as voltage follower with input step from V_{EE} to V_{CC} . Number specified is the slower of the positive and negative slew rates.

7. Input referred, $R_L = 100 \text{ k}\Omega$ connected to $V_S/2$. Each amp excited in turn with 1 kHz to produce $V_O = 3 V_{PP}$. (For Supply Voltages < 3 V, $V_O = V_{CC}$).

5 V DC ELECTRICAL CHARACTERISTICS (Note 8) Unless otherwise noted, all min/max limits are guaranteed for $T_A = 25^{\circ}C$, $V_S = 5$ V, $V_{CM} = V_S/2$, $V_O = V_S/2$ and $R_L > 1$ M Ω . Typical specifications represent the most likely parametric norm.

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Input Offset Voltage	V _{IO}	LMV931 (Single) (-40°C to +125°C)		1	6	mV
		LMV932 (Dual) (-40°C to +125°C)		1	7.5	
Input Offset Voltage Average Drift	TCV _{IO}			5.5		μV/°C
Input Bias Current	Ι _Β	−40°C to +125°C		< 1		nA
Input Offset Current	I _{IO}	−40°C to +125°C		< 1		nA
Supply Current (per	I _{CC}	In Active Mode		95	210	μΑ
Channel)		−40°C to +125°C			230	
Common-Mode	CMRR	0 V \leq V _{CM} \leq 3.8 V, 4.6 V \leq V _{CM} \leq 5.0 V	50	70		dB
Rejection Ratio		−40°C to +125°C	50			
		$-0.2 \text{ V} \leq \text{V}_{\text{CM}} \leq 0 \text{ V}, 5.0 \text{ V} \leq \text{V}_{\text{CM}} \leq 5.2 \text{V}$	50	70		
Power Supply	PSRR	$1.8~V~\leq~V^+~\leq~5~V,~V_{CM}=0.5~V$	50	70		dB
Rejection Ratio		−40°C to +125°C	50			
Input Common–Mode Voltage Range	Vсм	For CMRR \geq 50 dB and $T_A = 25^{\circ}C$	V _{EE} - 0.2	-0.2 to 5.3	V _{CC} + 0.2	V
		For CMRR \geq 50 dB and T _A = -40° C to $+85^{\circ}$ C	V _{EE}		V _{CC}	
		For CMRR \geq 50 dB and T _A = -40° C to $+125^{\circ}$ C	V _{EE} + 0.3		V _{CC} - 0.3	
Large Signal Voltage Gain LMV931 (Single)	A _V	R_L = 600 Ω to 2.5 V, V_O = 0.2 V to 4.8 V	88	102		dB
		−40°C to +125°C	87			
		R_L = 2 k Ω to 2.5 V, V_O = 0.2 V to 4.8 V	94	113		
		−40°C to +125°C	93			
Large Signal Voltage	A _V	R_L = 600 Ω to 2.5 V, V_O = 0.2 V to 4.8 V	81	90		
Gain LMV932 (Dual)		−40°C to +125°C	78			
		R_L = 2 k Ω to 2.5 V, V_O = 0.2 V to 4.8 V	85	100		
		−40°C to +125°C	82			
Output Swing	V _{OH}	R_L = 600 Ω to 2.5 V, V_{IN} = ±100 mV	4.855	4.89		V
		−40°C to +125°C	4.835			
	V _{OL}	R_L = 600 Ω to 2.5 V, V_{IN} = \pm 100 mV		0.12	0.16	
		−40°C to +125°C			0.18	
	V _{OH}	R_L = 2 k Ω to 2.5 V, V_{IN} = ±100 mV	4.945	4.967		
		−40°C to +125°C	4.935			
	V _{OL}	R_L = 2 k Ω to 2.5 V, V_{IN} = $\pm100~mV$		0.037	0.065	
		-40°C to +125°C			0.075	1
Output Short-Circuit	I _O	Sourcing, Vo = 0 V, V_{IN} = +100 mV	55	65		mA
Current	-40°C to +125°C 45					
		Sinking, Vo = 5 V, V_{IN} = -100 mV	58	80		
		-40°C to +125°C	45			

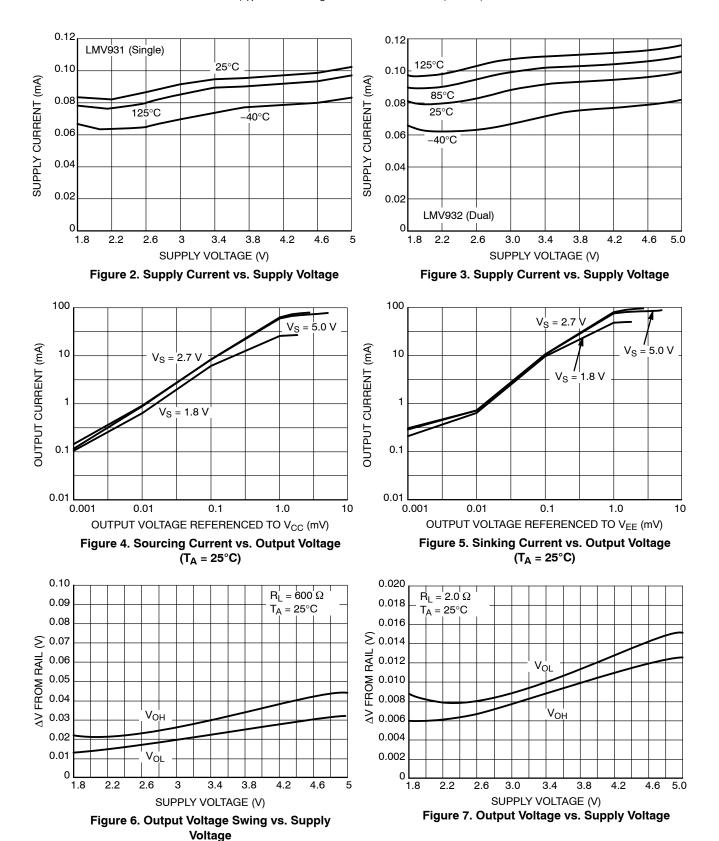
^{8.} Guaranteed by design and/or characterization.

5 V AC ELECTRICAL CHARACTERISTICS Unless otherwise specified, all limits are guaranteed for $T_A = 25$ °C, $V_S = 5$ V, $V_{CM} = V_S/2$, $V_C = V_S/2$ and $R_L > 1$ M Ω . Typical specifications represent the most likely parametric norm.

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Slew Rate	SR	(Note 9)		0.48		V/uS
Gain Bandwidth Product	GBWP			1.5		MHz
Phase Margin	Θm			65		0
Gain Margin	Gm			8		dB
Input-Referred Voltage Noise	e _n	f = 50 kHz, V _{CM} = 2 V		50		nV/√ Hz
Total Harmonic Distortion	THD	f = 1 kHz, A_V = +1, R_L = 600 Ω , V_O = 1 V_{PP}		0.022		%
Amplifier-to- Amplifier Isolation		(Note 10)		123		dB

Connected as voltage follower with input step from V_{EE} to V_{CC}. Number specified is the slower of the positive and negative slew rates.
 Input referred, R_L = 100 kΩ connected to V_S/2. Each amp excited in turn with 1 kHz to produce V_O = 3 V_{PP}. (For Supply Voltages < 3 V, V_O = V_{CC}).

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

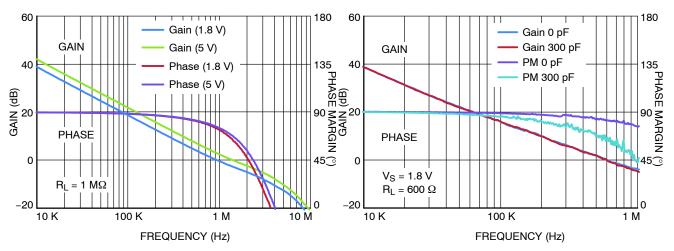


Figure 8. Open Loop Gain and Phase

Figure 9. Frequency Response vs. CL

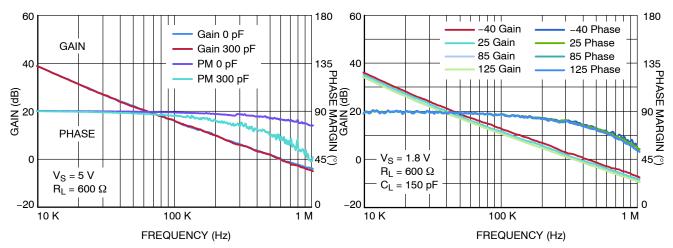


Figure 10. Frequency Response vs. CL

Figure 11. Gain and Phase vs. Temp

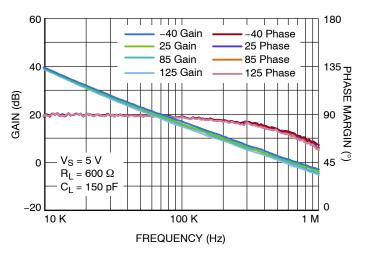


Figure 12. Gain and Phase vs. Temp

TYPICAL CHARACTERISTICS

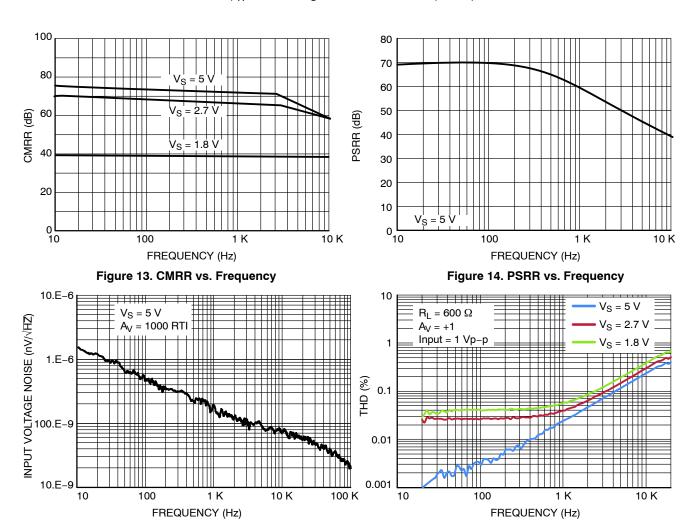


Figure 15. Input Voltage Noise vs. Frequency

Figure 16. THD vs. Frequency

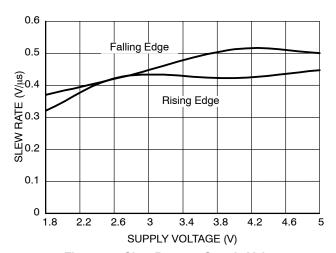


Figure 17. Slew Rate vs. Supply Voltage

TYPICAL CHARACTERISTICS

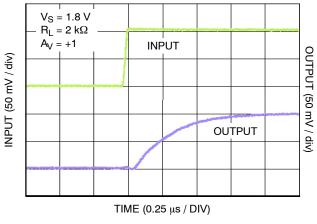


Figure 18. Small Signal Transient Response

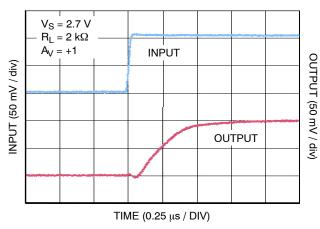


Figure 19. Small Signal Transient Response

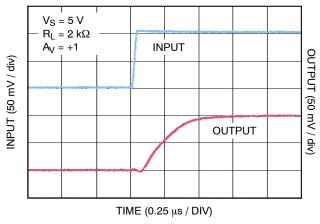


Figure 20. Small Signal Transient Response

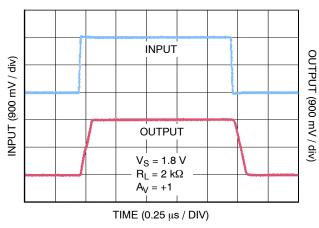


Figure 21. Large Signal Transient Response

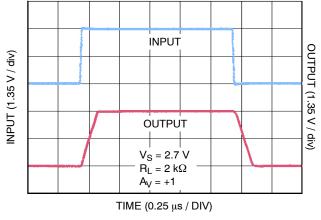


Figure 22. Large Signal Transient Response

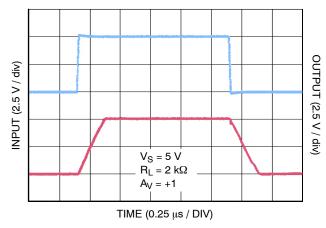
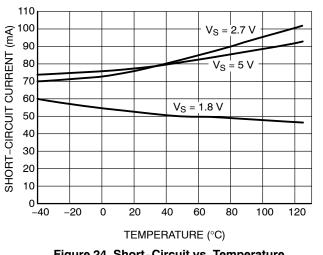


Figure 23. Large Signal Transient Response

TYPICAL CHARACTERISTICS

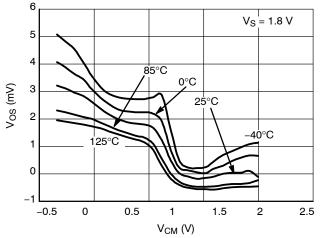
 $(T_A = 25^{\circ}C \text{ and } V_S = 5 \text{ V unless otherwise specified})$



110 100 SHORT-CIRCUIT CURRENT (mA) 90 V_S = 5 V 80 70 $V_S = 2.7 V$ 60 50 40 30 20 V_S = 1.8 V 10 0 -40 -20 60 80 100 120 TEMPERATURE (°C)

Figure 24. Short-Circuit vs. Temperature (Sinking)

Figure 25. Short-Circuit vs. Temperature (Sourcing)



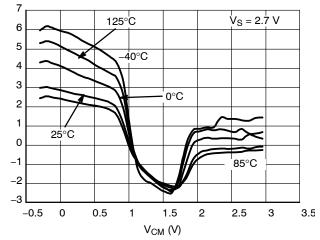
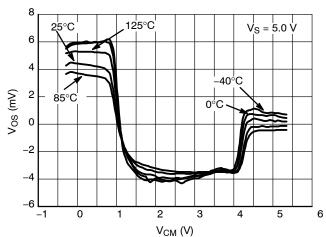


Figure 26. Offset Voltage vs. Common Mode Range V_{DD}

Figure 27. Offset Voltage vs. Common Mode Range



Vos (mV)

Figure 28. Offset Voltage vs. Common Mode Range

APPLICATION INFORMATION

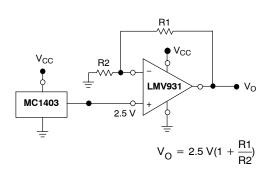


Figure 29. Voltage Reference

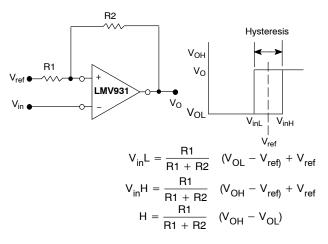


Figure 31. Comparator with Hysteresis

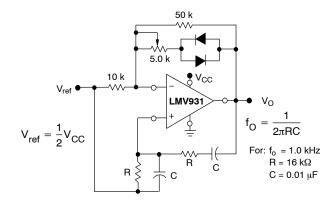
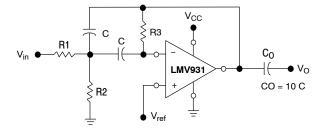


Figure 30. Wien Bridge Oscillator



Given: f_0 = center frequency $A(f_0)$ = gain at center frequency

Choose value f_0 , $\frac{C}{Q}$ Then: $R3 = \frac{Q}{\pi f_0 C}$ $R1 = \frac{R3}{2 A(f_0)}$ $R2 = \frac{R1 R3}{4Q^2 R1 - R3}$

For less than 10% error from operational amplifier, (($Q_O f_O$)/BW) < 0.1 where f_O and BW are expressed in Hz. If source impedance varies, filter may be preceded with voltage follower buffer to stabilize filter parameters.

Figure 32. Multiple Feedback Bandpass Filter

ORDERING INFORMATION

Order Number	Number of Channels	Number of Pins	Package Type	Shipping [†]
LMV931SQ3T2G	Single	5	SC70-5 (Pb-Free)	3000 / Tape & Reel
LMV931SN3T1G	Single	5	TSOP-5 (Pb-Free)	3000 / Tape & Reel
LMV932DMR2G	Dual	8	Micro8 (Pb-Free)	4000 / Tape & Reel
LMV932DR2G	Dual	8	SOIC-8 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





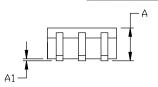
SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

DATE 11 APR 2023

NOTES:

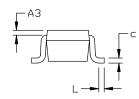
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSDLETE, NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS,
 OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

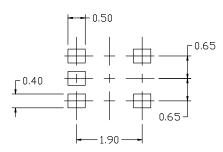
DIM	MILLIMETERS			
INITU	MIN.	N□M.	MAX.	
А	0.80	0.95	1.10	
A1			0.10	
A3		0.20 REF	•	
b	0.10	0.20	0.30	
C	0.10		0.25	
D	1.80	2.00	2,20	
Е	2.00	2.10	2.20	
E1	1.15	1.25	1.35	
е	0.65 BSC			
L	0.10	0.15	0.30	



5X b

◆ 0.2 M B M





RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1:
PIN 1. BASE
EMITTER
3. BASE
COLLECTOR
COLLECTOR

STYLE 2:
PIN 1. ANODE
2. EMITTER
3. BASE
4. COLLECTOR
5. CATHODE

STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1 STYLE 4:
PIN 1. SOURCE 1
2. DRAIN 1/2
3. SOURCE 1
4. GATE 1
5. GATE 2

STYLE 5:
PIN 1. CATHODE
2. COMMON ANODE
3. CATHODE 2
4. CATHODE 3
5. CATHODE 4

STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR STYLE 7:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE

5. EMITTER

STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

DOCUMENT NUMBER:

98ASB42984B

Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

DESCRIPTION: SC-88A (SC-70-5/SOT-353)

PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

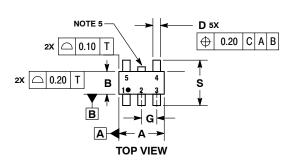
5. COLLECTOR 2/BASE 1

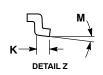


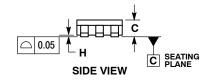


TSOP-5 **CASE 483 ISSUE N**

DATE 12 AUG 2020







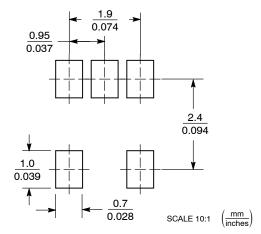


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- DIMENSIONING AND TOLERANCING PER ASME
 Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE
 MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A. OPTIONAL CONSTRUCTION: AN ADDITIONAL
- TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

	MILLIMETERS			
DIM	MIN	MAX		
Α	2.85	3.15		
В	1.35	1.65		
С	0.90	1.10		
D	0.25	0.50		
G	0.95	BSC		
Н	0.01	0.10		
J	0.10	0.26		
K	0.20	0.60		
М	0 °	10 °		
S	2.50	3.00		

SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*





XXX = Specific Device Code XXX = Specific Device Code

= Assembly Location = Date Code

= Year = Pb-Free Package

= Work Week W

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER: 98ARB18753C Electronic versions are uncontrolled except when accessed directly from the Document Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.				
	DESCRIPTION:	TSOP-5		PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.





SOIC-8 NB CASE 751-07 **ISSUE AK**

DATE 16 FEB 2011



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INC	INCHES	
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27 BSC		0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
M	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location = Wafer Lot = Year = Work Week W

= Pb-Free Package

XXXXXX XXXXXX AYWW AYWW Ŧ \mathbb{H} Discrete **Discrete** (Pb-Free)

XXXXXX = Specific Device Code = Assembly Location Α = Year ww = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

		Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	
DESCRIPTION:	SOIC-8 NB		PAGE 1 OF 2

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

SOIC-8 NB CASE 751-07 ISSUE AK

DATE 16 FEB 2011

STYLE 1: PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER	STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1	STYLE 3: PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1	STYLE 4: PIN 1. ANODE 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE
STYLE 5: PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE	STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE	STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd	STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE. #1
STYLE 9: PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON	STYLE 10: PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND	STYLE 11: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 8. DRAIN 1	STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
STYLE 13: PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN	STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN	STYLE 15: PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON	STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 7. COLLECTOR, DIE #2 8. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1
STYLE 17: PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC	STYLE 18: PIN 1. ANODE 2. ANODE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. CATHODE 8. CATHODE	STYLE 19: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. MIRROR 1	STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5 6. COMMON ANODE 7. COMMON ANODE 8. CATHODE 6	STYLE 22: PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3. COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND	STYLE 23: PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT 6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT	STYLE 24: PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE 6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE
STYLE 25: PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT	STYLE 26: PIN 1. GND 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC	STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN	STYLE 28: PIN 1. SW TO GND 2. DASIC OFF 3. DASIC SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN
STYLE 29: PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1	STYLE 30: PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1		

DOCUMENT NUMBER:	98ASB42564B	Printed versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOIC-8 NB		PAGE 2 OF 2

onsemi and ONSEMi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.



Micro8 CASE 846A-02 ISSUE K

DATE 16 JUL 2020









NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
- DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



MOUNTING FOOTPRINT

DIM	MI	MILLIMETERS			
ויונע	MIN.	N□M.	MAX.		
Α	-	-	1.10		
A1	0.05	0.08	0.15		
b	0.25	0.33	0.40		
c	0.13	0.18	0.23		
D	2.90	3.00	3.10		
Ε	2.90	3.00	3.10		
е	0.65 BSC				
HE	4.75	4.90	5.05		
L	0.40	0.55	0.70		

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code Α = Assembly Location

Υ = Year W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. SOURCE	PIN 1. SOURCE 1	PIN 1. N-SOURCE
SOURCE	2. GATE 1	2. N-GATE
SOURCE	3. SOURCE 2	3. P-SOURCE
GATE	4. GATE 2	4. P-GATE
DRAIN	5. DRAIN 2	5. P-DRAIN
DRAIN	6. DRAIN 2	6. P-DRAIN
7. DRAIN	7. DRAIN 1	7. N-DRAIN
8. DRAIN	8. DRAIN 1	8. N-DRAIN

DOCUMENT NUMBER:	98ASB14087C	Electronic versions are uncontrolled except when accessed directly from the Document Reposito Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	MICRO8		PAGE 1 OF 1	

ON Semiconductor and unare trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales